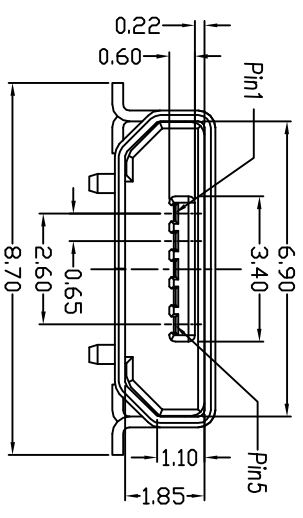
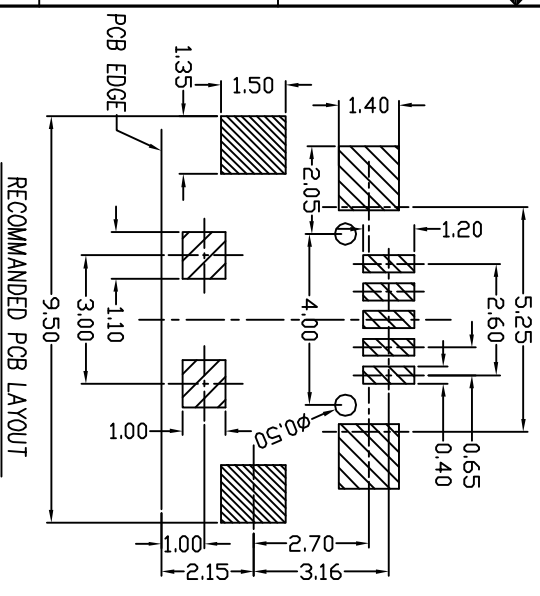
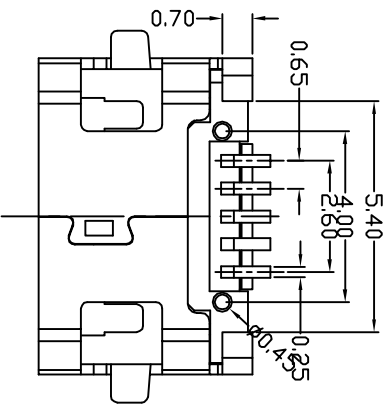
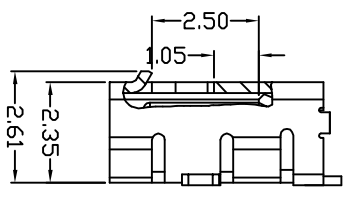
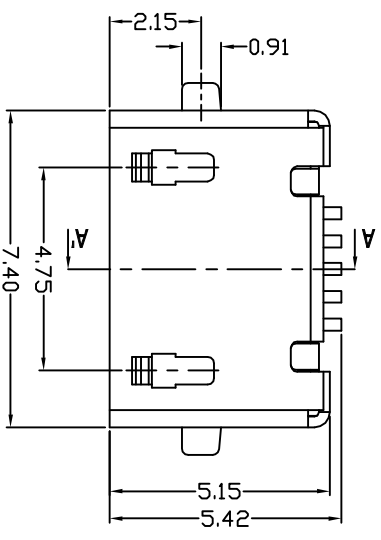
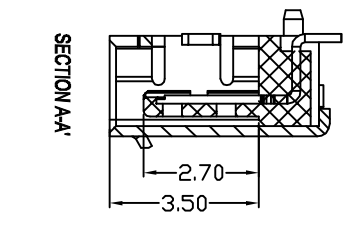
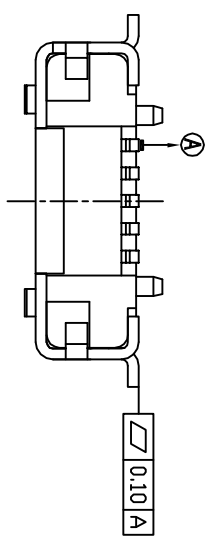


REV.	EQN NO	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



- Notes:
1. Materials:
    - 1.1 Housing: High temperature thermoplastic with g.f. UL94 v-0.
    - 1.2 Contact: copper alloy t=0.20mm.
    - 1.3 Shell: copper alloy t=0.25mm.
  2. Specifications:
    - 2.1. Current rating: 1 A Max.
    - 2.2. Dielectric withstanding: voltage: 100 V(ac) for 1 min.
    - 2.3. Contact resistance: 50 mW Max.
    - 2.4. Insulation resistance: 100 MW Min.
    - 2.5. Total mating force: 3.57 Kgf Max.
    - 2.6. Total unmating force: 1.0 Kgf Min. 0.81~2.05 Kgf Min. after 10000 insertion/extraction cycles
    - 2.7. Temperature range: -30°C~+80°C

PART NO: 1-MD05SMXXX-01		MATERIAL: SEE NOTE	
MODEL NO:		FINSH: SEE NOTE	
UNIT: mm	SIZE: A4	COLOR: SEE NOTE	
TOLERANCE UNSPECIFIED			
.x	±0.38	DR: ???	
.xx	±0.25	CHK:	
.xxx	±0.13	APP:	
ANG.	±2°	SCALE: 1:1	
TITLE: Micro usb 5P/F B Type SMT (外壳加焊盘, 脚长8.7)		SHEET: 1/1	
DWG NO: A107		REV: A	

深圳市创粤电子有限公司

